

General Description

The high current Press-Fit terminal blocks and spacers of the **PowerClamp** Series are designed for the solderless PCB or bus bar mount by the famous **SOFTPRESS** technique. This technology guarantees a very low contact resistance between the PCB and the **PowerClamp**

These **PowerClamp** components handle continuous currents from 100 up to 600 Amps and appear in different standard configurations:

H - Series – spacer without thread (through hole spacer) - (see this document)

D - Series – spacer with double press-fit zone

B - Series – terminal block with external thread (bolt)

N - Series – terminal block with internal thread (nut)

L - Series – terminal block with 90° mounting (horizontal thread or hole)

Various accessories allow the enlargement of the applications (see *accessories* and *applications*)



Technical Specifications

Type	Current rating ¹⁾	Ø i	Ø o	Ø e	Ø P	Height h ²⁾ Index h : [mm]	Insertion Force ³⁾ [N]	
H1004Z	150A	4.3	10.0	9.15		1.1 = Z	900	
H1105Z	160A	5.3	11.0	10.15			1'000	
H1206Z	180A	6.4	12.0	11.15			1'100	
H1003h	150A	3.3	8.0	10.0	9.15	3=A 4=B 5=C 6=D 7=E 8=F 9=G 10=H 11=I 12=J 13=K 14=L 15=M 16=N 17=O 18=P 19=Q 20=R	900	
H1104h	160A	4.3	9.0	11.0	10.15		1'000	
H1205h	180A	5.3	10.0	12.0	11.15		1'100	
H1506h	230A	6.4	13.0	15.0	14.15		1'400	
H1908h	300A	8.4	17.0	19.0	18.15		1'800	
H2310h	370A	10.5	21.0	23.0	22.15		2'200	
Material		CuZn40Pb2 / CW617N						
Plating		2 µ BroxAlloy						

¹⁾ The max. current depends on the PCB copper thickness. ²⁾ On request other heights available.
³⁾ The Insertion Force depends on the PCB.

	Recommended PCB Configuration PCB thickness: 1.5 – 3.2 mm drilled hole = D +0.02 / -0.05 mm Cu plating = 25 - 45 µm Sn plating = <15 µm	H-Series H1003h, H1004Z H1104h, H1105Z H1205h, H1206Z H1506h H1908h H2310h	D +0.02/-0.05 [mm]	Ø [mm] of recommended rough milling	Instead of milling, the hole can be made by nibbling

For PCB Configuration see also: www.broxing.com/Applications/dt0101_plated_holes.pdf